

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6665924

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HYUNG KEUN KIM	04/05/2021
JUN KU AHN	04/05/2021
JUN YOUNG LIM	04/05/2021
SUNG LAE CHO	04/05/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SK HYNIX INC.
<b>Street Address:</b>	2091, GYEONGCHUNG-DAERO, BUBAL-EUB
<b>Internal Address:</b>	GYEONGGI-DO
<b>City:</b>	ICHEON
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	17336
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17234483
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	100SK1038US
<b>NAME OF SUBMITTER:</b>	AUTUMN DIAZ
<b>SIGNATURE:</b>	/AUTUMN DIAZ/
<b>DATE SIGNED:</b>	04/20/2021
<b>Total Attachments: 2</b>	
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source=Po201590HD_Assignment_and_Declaration#page2.tif	

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, the below named individual(s), hereinafter referred to as "Assignors," are the inventor(s) of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR DEVICE AND  
MANUFACTURING METHOD OF THE  
SEMICONDUCTOR DEVICE

Filing Date:

Application No.:

WHEREAS, SK hynix Inc. of 2091, Gyeongchung-daero, Bubal-eup, Icheon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignees, and Assignees' successors and assigns, all their right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignees as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request AMPACC Law Group, PLLC, 6100 219<sup>th</sup> Street SW, Suite 580, Mountlake Terrace, WA 98043, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

April 5, 2021  
Date

Hyung Keun, Kim  
Name: Hyung Keun KIM

April 5, 2021  
Date

Jun Ku, AHN  
Name: Jun Ku AHN

April 5, 2021  
Date

Jun young, Lim  
Name: Jun Young LIM

April 5, 2021  
Date

Sung Lac CHO  
Name: Sung Lac CHO

SK hynix  
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